



Welcome United States Patent and Trademark Office

☐ Search Results

BROWSE

SEARCH

IEEE XPLORE GUIDE

Results for "((aluminum nitride)<in>metadata) and thermal conductivity"

e-mail

Your search matched 105 of 1382205 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

» Search Options

[View Session History](#)
[New Search](#)

Modify Search

((aluminum nitride)<in>metadata) and thermal conductivity

☐ Check to search only within this results set
Display Format: ☒ Citation ☐ Citation & Abstract

» Key

IEEE JNL IEEE Journal or Magazine

IEEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

[Select All](#) [Deselect All](#)

View: 1-25 | 26-5

- ☐ 1. **Hydrolytically stable aluminum nitride as a filler material for polymer based packaging**
Howard, K.E.; Knudsen, A.K.;
Advanced Packaging Materials. Proceedings., 3rd International Symposium on
9-12 March 1997 Page(s):98 - 101
Digital Object Identifier 10.1109/ISAPM.1997.581266
[AbstractPlus](#) | Full Text: [PDF](#)(256 KB) IEEE CNF
[Rights and Permissions](#)
- ☐ 2. **Prototype packages in aluminum nitride for high performance electronic**
Lodge, K.J.; Sparrow, J.A.; Perry, E.D.; Logan, E.A.; Goosey, M.T.; Pedder, D.
C.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on
Trans. on Components, Packaging, and Manufacturing Technology, Part A, B,
Volume 13, Issue 4, Dec. 1990 Page(s):633 - 638
Digital Object Identifier 10.1109/33.62572
[AbstractPlus](#) | Full Text: [PDF](#)(844 KB) IEEE JNL
[Rights and Permissions](#)
- ☐ 3. **Effects of radiofrequency energy on human chondromalacic cartilage: an insulation material properties**
Meyer, M.L.; Yan Lu; Markel, M.D.;
[Biomedical Engineering, IEEE Transactions on](#)
Volume 52, Issue 4, Apr 2005 Page(s):702 - 710
Digital Object Identifier 10.1109/TBME.2005.845155
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(4056 KB) IEEE JNL
[Rights and Permissions](#)
- ☐ 4. **High thermally conductive underfill for flip-chip applications**
Suzuki, K.; Suzuki, O.; Muramatsu, K.; Yuda, T.; Isobe, K.; Maruyama, H.; Fuku
[Advanced Packaging Materials: Processes, Properties and Interfaces, 2001. P](#)
[International Symposium on](#)
11-14 March 2001 Page(s):46 - 50
Digital Object Identifier 10.1109/ISAOM.2001.916547
[AbstractPlus](#) | Full Text: [PDF](#)(236 KB) IEEE CNF
[Rights and Permissions](#)

5. Aluminum nitride packaging

- Ishida, M.; Hasegawa, T.; Iwaida, T.; Knudsen, A.;
Advanced Packaging Materials: Processes, Properties and Interfaces, 1999. P
International Symposium on
 14-17 March 1999 Page(s):133 - 135
 Digital Object Identifier 10.1109/ISAPM.1999.757300
[AbstractPlus](#) | Full Text: [PDF](#)(180 KB) IEEE CNF
[Rights and Permissions](#)
6. **3-D interconnected porous AlN composite: a viable substrate for electron**
 Jin Yong Kim; Kumta, P.N.;
Aerospace and Electronics Conference, 1998. NAECON 1998. Proceedings of
National
 13-17 July 1998 Page(s):656 - 665
 Digital Object Identifier 10.1109/NAECON.1998.710225
[AbstractPlus](#) | Full Text: [PDF](#)(1700 KB) IEEE CNF
[Rights and Permissions](#)
7. **Moisture resistant aluminum nitride filler for high thermal conductivity m**
molding compounds
 Gallo, A.A.; Bischof, C.S.; Howard, K.E.; Dunmead, S.D.; Anderson, S.A.;
Electronic Components and Technology Conference, 1996. Proceedings., 46th
 28-31 May 1996 Page(s):335 - 342
 Digital Object Identifier 10.1109/ECTC.1996.517410
[AbstractPlus](#) | Full Text: [PDF](#)(744 KB) IEEE CNF
[Rights and Permissions](#)
8. **Dielectric breakdown in aluminium nitride**
 Ruemenapp, T.; Peier, D.;
High Voltage Engineering, 1999. Eleventh International Symposium on (Conf. I
 Volume 4, 23-27 Aug. 1999 Page(s):373 - 376 vol.4
[AbstractPlus](#) | Full Text: [PDF](#)(364 KB) IEEE CNF
9. **Aluminum Nitride-An Alternative Ceramic Substrate for High Power Appli**
Microcircuits
 Werdecker, W.; Aldinger, F.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [
Trans. on Components, Packaging, and Manufacturing Technology, Part A, B,
 Volume 7, Issue 4, Dec 1984 Page(s):399 - 404
[AbstractPlus](#) | Full Text: [PDF](#)(1048 KB) IEEE JNL
[Rights and Permissions](#)
10. **Influence of the grain boundary phase on the mechanical strength at alur**
substrate surfaces
 Asai, H.; Takahashi, T.;
Advanced Packaging, IEEE Transactions on [see also Components, Packagin
Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions c
 Volume 23, Issue 3, Aug. 2000 Page(s):452 - 460
 Digital Object Identifier 10.1109/6040.861560
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(540 KB) IEEE JNL
[Rights and Permissions](#)
11. **The electrical properties of oxides-added thick-film resistors on aluminu**
substrates
 Ming-Liang Hsieh; Lih-Shan Chen;
Electronic Materials and Packaging, 2002. Proceedings of the 4th Internationa
 4-6 Dec. 2002 Page(s):468 - 471
 Digital Object Identifier 10.1109/EMAP.2002.1188884
[AbstractPlus](#) | Full Text: [PDF](#)(287 KB) IEEE CNF
[Rights and Permissions](#)

12. **Evaluation of aluminum nitride based RF lossy dielectrics for use in high microwave devices**
 Kirshner, M.F.; Turek, L.; Pekrul, E.;
[Vacuum Electronics Conference, 2002. IVEC 2002. Third IEEE International 23-25 April 2002](#) Page(s):36 - 37
 Digital Object Identifier 10.1109/IVELEC.2002.999247
[AbstractPlus](#) | [Full Text: PDF\(225 KB\)](#) | [IEEE CNF](#)
[Rights and Permissions](#)
13. **High thermal conductivity aluminum nitride ceramics for high power mic**
 Savrun, E.; Nguyen, V.; Abe, D.K.;
[Vacuum Electronics Conference, 2002. IVEC 2002. Third IEEE International 23-25 April 2002](#) Page(s):34 - 35
 Digital Object Identifier 10.1109/IVELEC.2002.999246
[AbstractPlus](#) | [Full Text: PDF\(280 KB\)](#) | [IEEE CNF](#)
[Rights and Permissions](#)
14. **Thick Film and Direct Bond Copper Forming Technologies for Aluminum Substrate**
 Iwase, N.; Anzai, K.; Shinozaki, K.; Hirao, O.; Troung Thanh; Sugiura, Y.;
[Components, Hybrids, and Manufacturing Technology, IEEE Transactions on Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, Volume 8, Issue 2, Jun 1985](#) Page(s):253 - 258
[AbstractPlus](#) | [Full Text: PDF\(1128 KB\)](#) | [IEEE JNL](#)
[Rights and Permissions](#)
15. **Titanium nitride-molybdenum metallizing method for aluminum nitride**
 Asai, H.; Ueno, F.; Iwase, N.; Sato, H.; Mizunoya, N.; Kimura, T.; Endo, K.; Tai Sugiura, Y.;
[Components, Hybrids, and Manufacturing Technology, IEEE Transactions on Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, Volume 13, Issue 2, June 1990](#) Page(s):457 - 461
 Digital Object Identifier 10.1109/33.56185
[AbstractPlus](#) | [Full Text: PDF\(436 KB\)](#) | [IEEE JNL](#)
[Rights and Permissions](#)
16. **Advanced ceramic substrates for multichip modules with multilevel thin interconnects**
 Foster, B.C.; Bachner, F.J.; Tormey, E.S.; Occhionero, M.A.; White, P.A.;
[Components, Hybrids, and Manufacturing Technology, IEEE Transactions on Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, Volume 14, Issue 4, Dec. 1991](#) Page(s):784 - 789
 Digital Object Identifier 10.1109/33.105134
[AbstractPlus](#) | [Full Text: PDF\(748 KB\)](#) | [IEEE JNL](#)
[Rights and Permissions](#)
17. **Excimer laser machining and metallization of vias in aluminum nitride**
 Lumpp, J.K.; Allen, S.D.;
[Components, Packaging, and Manufacturing Technology, Part B: Advanced P Transactions on \[see also Components, Hybrids, and Manufacturing Technolo Transactions on\]](#)
 Volume 20, Issue 3, Aug. 1997 Page(s):241 - 246
 Digital Object Identifier 10.1109/96.618223
[AbstractPlus](#) | [References](#) | [Full Text: PDF\(164 KB\)](#) | [IEEE JNL](#)
[Rights and Permissions](#)
18. **Numerical study of self-heating effects of MOSFETs fabricated on SOAN**
 Ming Zhu; Peng Chen; Fu, R.K.-Y.; Zhenghua An; Chenglu Lin; Chu, P.K.;


[Electron Devices, IEEE Transactions on](#)
Volume 51, Issue 6, June 2004 Page(s):901 - 906
Digital Object Identifier 10.1109/TED.2004.827362
[AbstractPlus](#) | [References](#) | [Full Text: PDF\(480 KB\)](#) IEEE JNL
[Rights and Permissions](#)

19. **Performance and analysis of an aluminium nitride isolation resistor**
Karamitsos, N.; Gibson, A.A.P.;
[Microwaves, Antennas and Propagation, IEE Proceedings -](#)
Volume 142, Issue 3, June 1995 Page(s):282 - 284
[AbstractPlus](#) | [Full Text: PDF\(216 KB\)](#) IEE JNL
20. **Hermetic metallization of aluminum nitride for RF windows**
Savrun, E.; Nguyen, V.;
[Vacuum Electronics Conference, 2004. IVEC 2004. Fifth IEEE International](#)
27-29 April 2004 Page(s):38 - 39
[AbstractPlus](#) | [Full Text: PDF\(458 KB\)](#) IEEE CNF
[Rights and Permissions](#)
21. **High thermal conductivity aluminum nitride ceramics for high power mic**
Savrun, E.; Nguyen, V.; Gilmore, N.;
[Vacuum Electronics Conference, 2004. IVEC 2004. Fifth IEEE International](#)
27-29 April 2004 Page(s):45 - 46
[AbstractPlus](#) | [Full Text: PDF\(463 KB\)](#) IEEE CNF
[Rights and Permissions](#)
22. **High thermal conductivity, lossy aluminum nitride dielectrics**
Savrun, E.; Abe, D.;
[Vacuum Electronics Conference, 2000. Abstracts, International](#)
2-4 May 2000 Page(s):2 pp.
Digital Object Identifier 10.1109/OVE:EC.2000.847520
[AbstractPlus](#) | [Full Text: PDF\(456 KB\)](#) IEEE CNF
[Rights and Permissions](#)
23. **Analysis of self-heating effects on partially depleted silicon on aluminum MOSFETs**
Osman, M.A.; Osman, A.A.;
[High Temperature Electronics Conference, 1998. HITEC, 1998 Fourth Internal](#)
14-18 June 1998 Page(s):169 - 171
Digital Object Identifier 10.1109/HITEC.1998.676782
[AbstractPlus](#) | [Full Text: PDF\(200 KB\)](#) IEEE CNF
[Rights and Permissions](#)
24. **An aluminum nitride package for 600°C and beyond**
Savrun, E.; Toy, C.;
[High Temperature Electronics Conference, 1998. HITEC, 1998 Fourth Internal](#)
14-18 June 1998 Page(s):265 - 268
Digital Object Identifier 10.1109/HITEC.1998.676801
[AbstractPlus](#) | [Full Text: PDF\(380 KB\)](#) IEEE CNF
[Rights and Permissions](#)
25. **Reliability of aluminum-nitride filled mold compound**
Tracy, D.; Nguyen, L.; Giberti, R.; Gallo, A.; Bischof, C.; Sweet, J.N.; Hsia, A.V
[Electronic Components and Technology Conference, 1997. Proceedings., 47th](#)
18-21 May 1997 Page(s):72 - 77
Digital Object Identifier 10.1109/ECTC.1997.606148
[AbstractPlus](#) | [Full Text: PDF\(560 KB\)](#) IEEE CNF
[Rights and Permissions](#)

View: **1-25** | 26-5

[Help](#) [Contact Us](#) [Privacy &](#)

© Copyright 2006 IEEE -

indexed by
 **nspec**